

Part Number: **BZX84CxxT-p-F (Date Code 0740+)**
Weight (mg): 3

p = package designator
See Data Sheet

XX= 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 2V4,
2V7, 30, 33, 36, 39, 3V0, 3V3, 3V6, 3V9, 4V3,
4V7, 5V1, 5V6, 6V2, 6V8, 7V5, 8V2, 9V1

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	2.28%	0.0571	1000000	22836
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	39.95%	0.9988	576500	230286
		Ni	7440-02-0	41.00%			410000	163777
		Mn	7439-96-5	0.60%			6000	2397
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	399
		Co	7440-48-4	0.50%			5000	1997
		Si	7440-21-3	0.15%			1500	599
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.20%	0.0299	1000000	11958
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.51%	0.0128	1000000	5119
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	54.72%	1.3682	690000	377563
		Epoxy Resin	29690-82-2	14.00%			140000	76607
		Phenol Resin	9003-35-4	7.00%			70000	38303
		Mg(OH)2	1309-42-8	8.00%			80000	43775
		C	1333-86-4	0.20%			2000	1094
		others	----	1.80%			18000	9849
		Tin	7440-31-5	100.00%			1000000	13438
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.34%	0.0336	1000000	13438
				Total	100.00	2.5004		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |